

AMENDMENTS TO THE CLAIMS

The following listing of claims will replace all prior versions, and listing of claims in the application:

LISTING OF CLAIMS:

Claim 1 (currently amended) A method of separating a sapphire substrate ~~and from~~ a thin film overlaying a top side of said sapphire substrate, comprising the steps of:

providing a laser array ~~over said sapphire substrate~~, said laser array emitting a plurality of laser ~~lights and said plurality of laser lights at least partially penetrating~~ light beams toward a back side of said sapphire substrate ~~and being absorbed for absorption~~ by said thin film;

irradiating said thin film with said plurality of light beams from said laser array through said sapphire substrate; and

separating said sapphire substrate and said thin film.

Claim 2 (currently amended) The method according to Claim 1, wherein each of said plurality of laser ~~lights~~ light beams has a wavelength of about 327 nm.

Claim 3 (original) The method according to Claim 1, wherein the step of irradiating said thin film is irradiating on an interface of said thin film with said sapphire substrate.

Claim 4 (currently amended) The method according to Claim 1, wherein the step of providing a laser array includes the step of providing said laser array ~~has~~ having a predetermined dimension to illuminate an area equivalent to an area of said sapphire substrate and said thin film.

Claim 5 (currently amended) A method of separating a substrate ~~and from~~ a thin film overlying a top side of said substrate, comprising the steps of:

providing a laser array ~~over said substrate~~, said laser array emitting a plurality of laser lights ~~and said plurality of laser lights at least partially penetrating~~ light beams toward a back side of said substrate and ~~being absorbed~~ said substrate being substantially transparent to said plurality of laser light beams for absorption of said plurality of laser light beams by said thin film;

irradiating said thin film with said laser array through said substrate;
and

separating said substrate and said thin film.

Claim 6 (currently amended) The method according to Claim 5, wherein the step of irradiating said thin film ~~is irradiating an interface~~ includes the step of providing an optical grating between said thin film laser array and said substrate and irradiating said thin film through said grating and said substrate to provide a uniform striped pattern of irradiation.

Claim 7 (currently amended) The method according to Claim 5, wherein the step of providing a laser array includes the step of providing said laser array has having a predetermined dimension to illuminate an area equivalent to an area of said substrate and said thin film.

Claims 8-9 (cancelled).